



Product Change Notification

107813 – 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 107813 – 00
Change Title: Introduction of Second Assembly Location for Intel® Demodulator Products: CE6353, CE6230, CE6231, CE6250 and CE62521, PCN 107813-00, Product Marking and Additional Assembly Site
Date of Publication: August 22, 2007

Key Characteristics of the Change:

Product Marking
Manufacturing Site

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Mar 31, 2008
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Description of Change to the Customer:

In order to meet demand, ensure continuity of supply and remain competitive on cost, Intel is announcing the addition of a second assembly location in China for the products detailed below.

Customer Impact of Change and Recommended Action:

There is no change to form, fit or function of the affected parts. Assembly location will be identifiable by the country of origin.

Products Affected / Intel Ordering Codes:

Affected Product Code	Affected S-Spec	Affected MM#
WJMT352	S L9G4	882169
WJCE6353	S L9G5	882170
WJMT352		882188
WJCE6353		882206
WJCE6230	Q 691	882770
WJCE6230	S L9KS	882771
WJCE6230	Q 692	882772
WJCE6231	Q 693	882774
WJCE6231	Q 694	882775
WJCE6231	S L9KT	882776
WJCE6230		883098
WJCE6231		883101
WJCE6353	Q 760	885313
WJCE6230	S LA34	888059
WJCE6231	S LA35	888061
WJCE6250	Q 892	888078
WJCE6250	S LA36	888093
WJCE6251	Q 936	888881
WJCE6251	S LA66	888887
WJCE6250		892547
WJCE6251		892548

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:

Revision Number:

Reason:

August 22, 2007

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Originally Published PCN